

| | |
|--------------------|--------|
| V_{DSS} | 650V |
| $R_{DS(on)}(Max.)$ | 0.205Ω |
| I_D | ±20A |
| P_D | 231W |

●Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating ; RoHS compliant

●Application

Switching

●Outline

LPT(S)



●Inner circuit



●Packaging specifications

| | |
|---------------------------|---------------|
| Packing | Embossed Tape |
| Packing code | TL |
| Marking | R6520KNJ |
| Basic ordering unit (pcs) | 1000 |

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|---|------------------------|-------------|------|
| Drain - Source voltage | V_{DSS} | 650 | V |
| Continuous drain current ($T_c = 25^\circ\text{C}$) | I_D^{*1} | ±20 | A |
| Pulsed drain current | I_{DP}^{*2} | ±60 | A |
| Gate - Source voltage | static | ±20 | V |
| | AC($f > 1\text{Hz}$) | ±30 | V |
| Avalanche current, single pulse | I_{AS} | 3.4 | A |
| Avalanche energy, single pulse | E_{AS}^{*3} | 444 | mJ |
| Power dissipation ($T_c = 25^\circ\text{C}$) | P_D | 231 | W |
| Junction temperature | T_j | 150 | °C |
| Operating junction and storage temperature range | T_{stg} | -55 to +150 | °C |

● Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|--|-----------------|--------|------|------|------|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - case | R_{thJC}^{*4} | - | - | 0.54 | °C/W |
| Thermal resistance, junction - ambient | R_{thJA}^{*5} | - | - | 80 | °C/W |
| Soldering temperature, wavesoldering for 10s | T_{sold} | - | - | 265 | °C |

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|-------------------|--|--------|-------|-----------|---------------|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 1mA$ | 650 | - | - | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 650V, V_{GS} = 0V$ $T_j = 25^\circ\text{C}$ | - | - | 100 | μA |
| | | $T_j = 125^\circ\text{C}$ | - | - | 1000 | |
| Gate - Source leakage current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ± 100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 630\mu\text{A}$ | 3 | - | 5 | V |
| Static drain - source on - state resistance | $R_{DS(on)}^{*6}$ | $V_{GS} = 10V, I_D = 9.5A$ $T_j = 25^\circ\text{C}$ | - | 0.185 | 0.205 | Ω |
| | | $T_j = 125^\circ\text{C}$ | - | - | - | |
| Gate resistance | R_G | $f = 1\text{MHz}, \text{open drain}$ | - | 2.4 | - | Ω |

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|------------------------------|-------------------|-------------------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Input capacitance | C_{iss} | $V_{GS} = 0V$ | - | 1550 | - | pF |
| Output capacitance | C_{oss} | $V_{DS} = 25V$ | - | 1450 | - | |
| Reverse transfer capacitance | C_{rss} | $f = 1\text{MHz}$ | - | 45 | - | |
| Turn - on delay time | $t_{d(on)}^{*6}$ | $V_{DD} \approx 300V, V_{GS} = 10V$ | - | 30 | - | ns |
| Rise time | t_r^{*6} | $I_D = 10A$ | - | 50 | - | |
| Turn - off delay time | $t_{d(off)}^{*6}$ | $R_L \approx 30\Omega$ | - | 75 | - | |
| Fall time | t_f^{*6} | $R_G = 10\Omega$ | - | 30 | - | |

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------|-----------------|----------------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Total gate charge | Q_g^{*6} | $V_{DD} \approx 300V$ | - | 40 | - | nC |
| Gate - Source charge | Q_{gs}^{*6} | $I_D = 20A$ | - | 10 | - | |
| Gate - Drain charge | Q_{gd}^{*6} | $V_{GS} = 10V$ | - | 17 | - | |
| Gate plateau voltage | $V_{(plateau)}$ | $V_{DD} \approx 300V, I_D = 20A$ | - | 6.8 | - | V |

*1 Limited only by maximum channel temperature allowed.

*2 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 $L \doteq 70\text{mH}$, $V_{DD} = 50V$, $R_G = 25\Omega$, STARTING $T_j = 25^\circ\text{C}$

*4 $T_C = 25^\circ\text{C}$

*5 Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

*6 Pulsed

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|-------------------------------|---------------|---|--------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| Source current | I_S^{*1} | $T_C = 25^\circ\text{C}$ | - | - | 20 | A |
| Pulsed source current | I_{SP}^{*2} | | - | - | 60 | A |
| Source-Drain voltage | V_{SD}^{*6} | $V_{GS} = 0\text{V}, I_S = 20\text{A}$ | - | - | 1.5 | V |
| Reverse recovery time | t_{rr}^{*6} | $I_S = 20\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ | - | 500 | - | ns |
| Reverse recovery charge | Q_{rr}^{*6} | | - | 8 | - | μC |
| Peak reverse recovery current | I_{rr}^{*6} | | - | 32 | - | A |

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

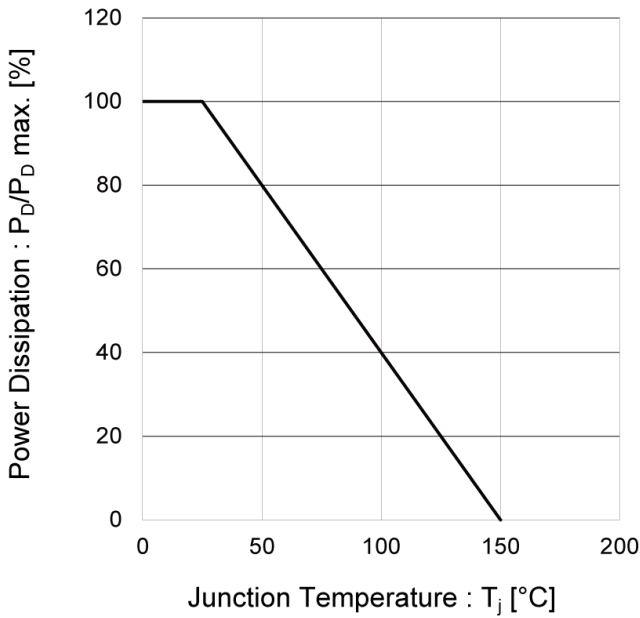


Fig.2 Drain Current Derating Curve

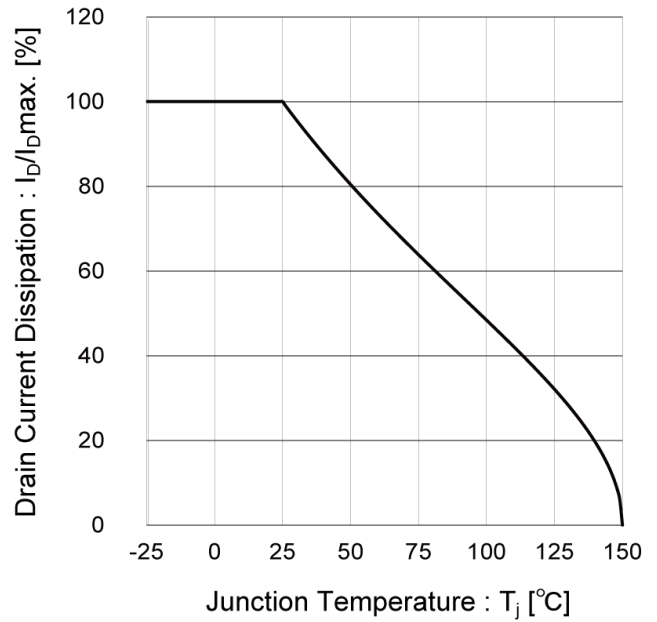


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

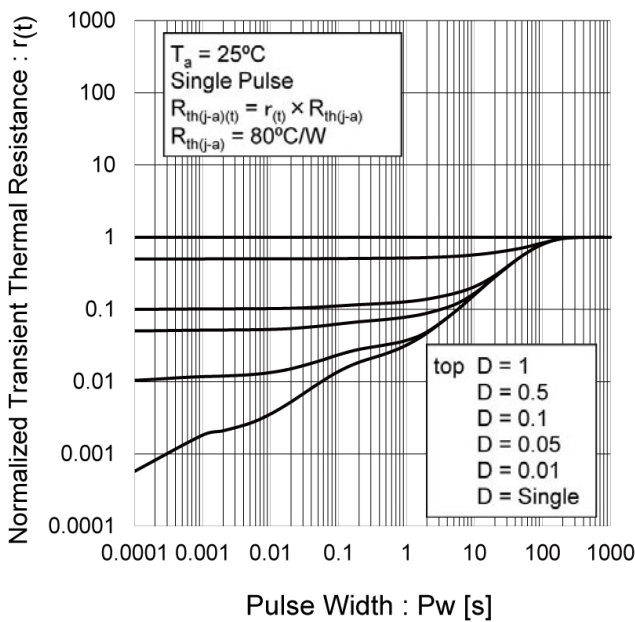
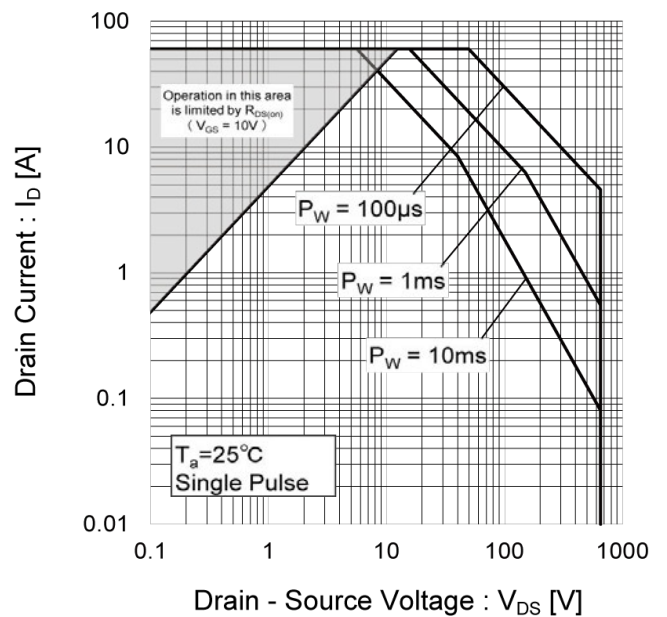


Fig.4 Maximum Safe Operating Area



●Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature



Fig.6 Breakdown Voltage vs. Junction Temperature

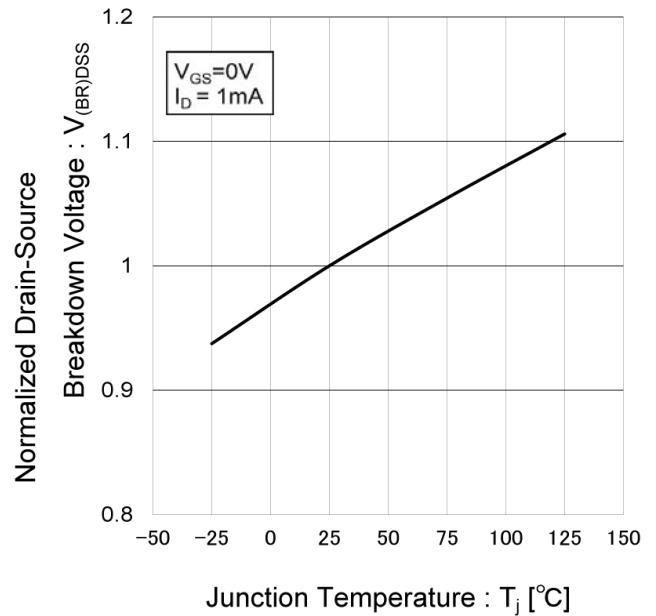


Fig.7 Typical Output Characteristics(I)

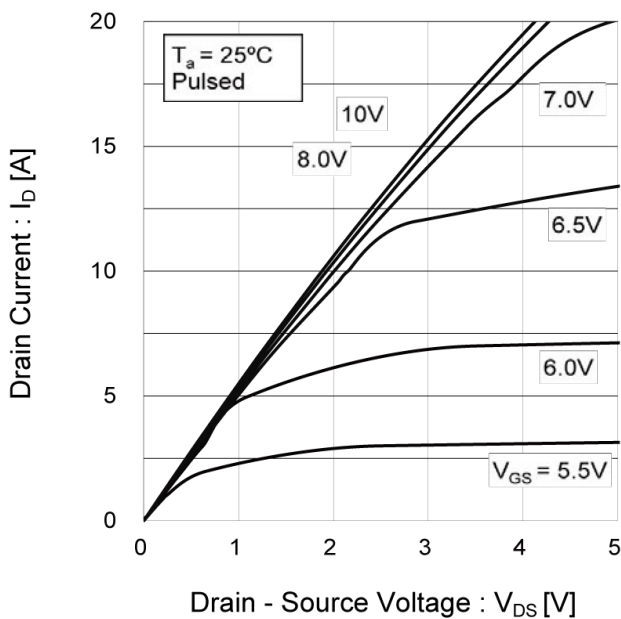
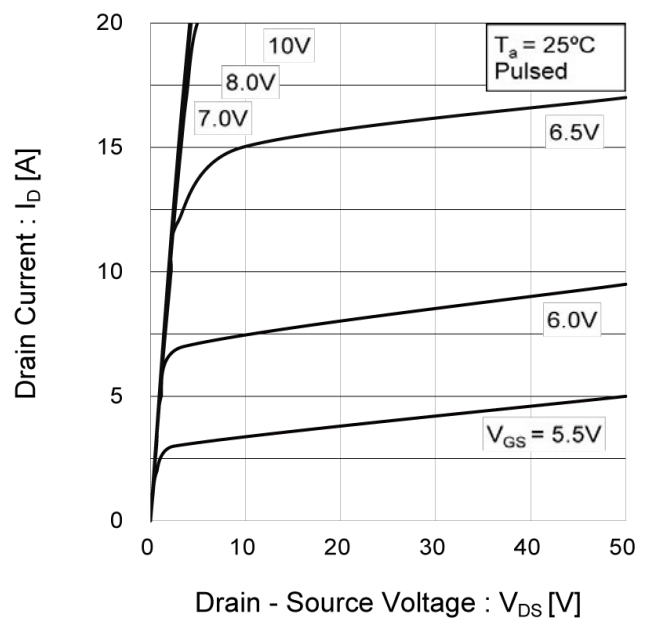


Fig.8 Typical Output Characteristics(II)



● Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

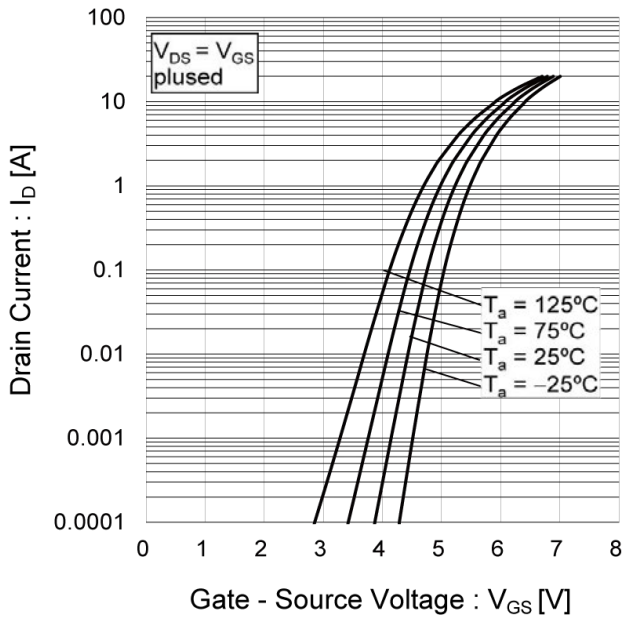


Fig.10 Normalized Gate Threshold Voltage vs Junction Temperature

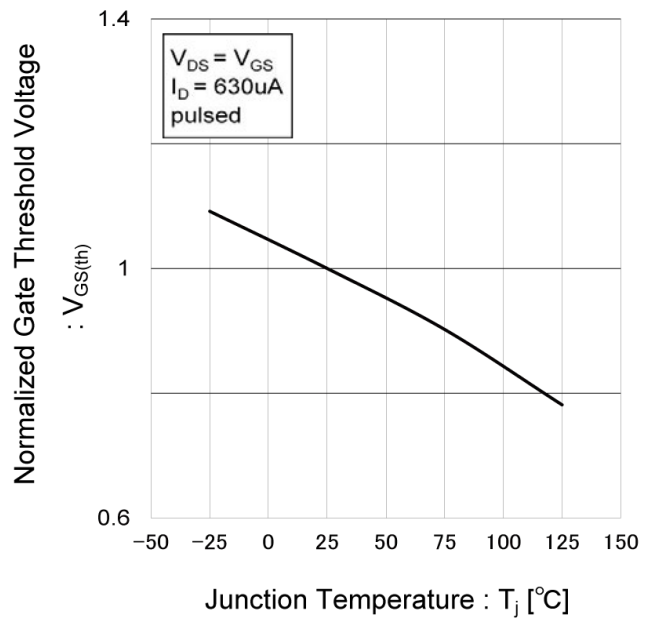


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

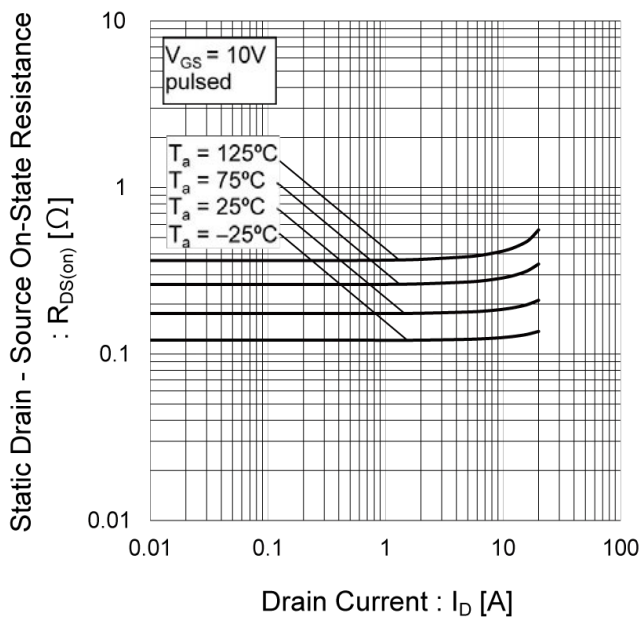
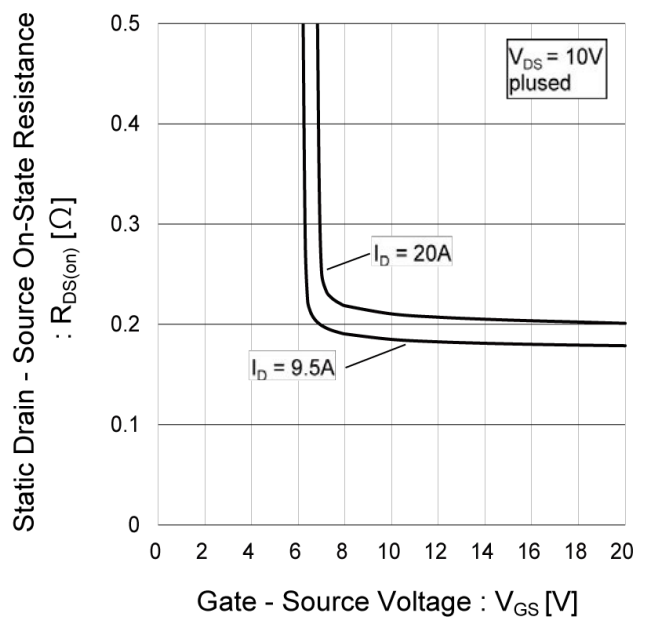


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

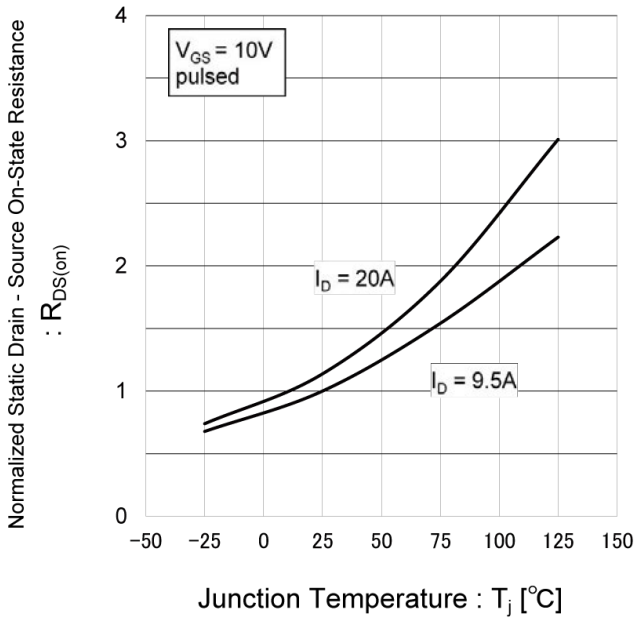


Fig.14 Typical Capacitance vs. Drain - Source Voltage

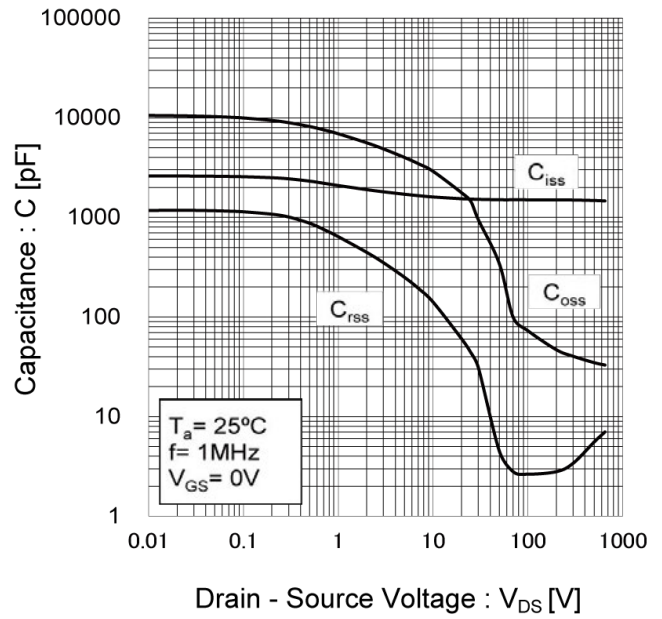


Fig.15 Switching Characteristics

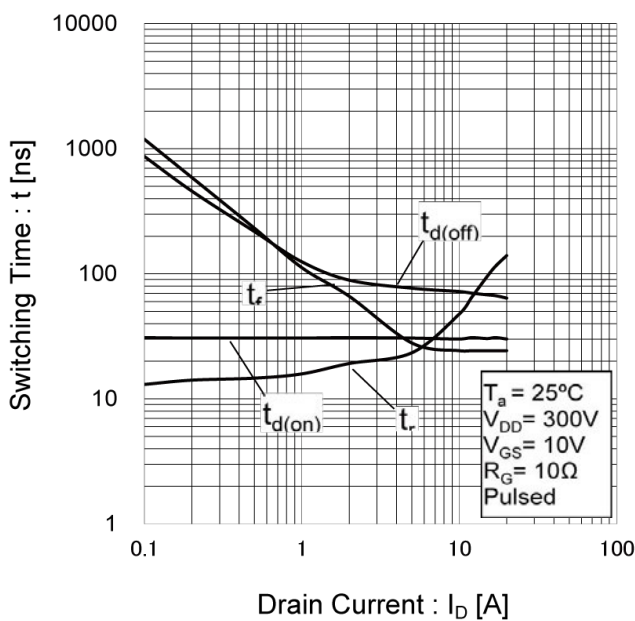
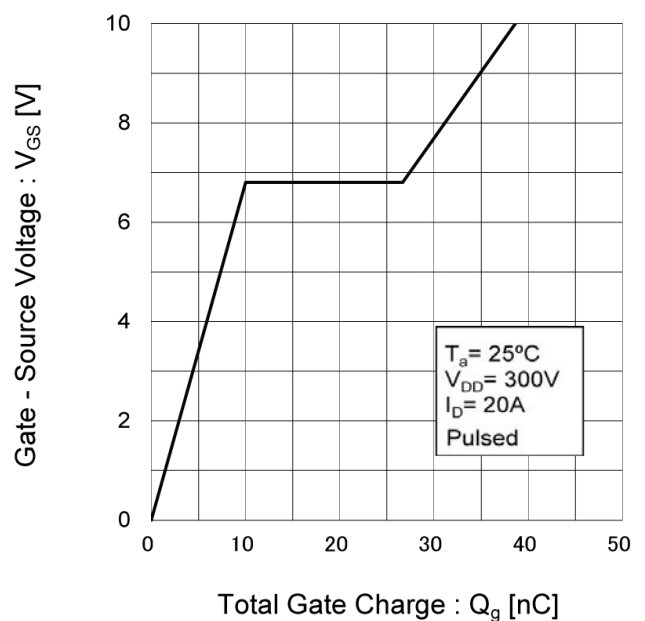


Fig.16 Typical Gate Charge



● Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

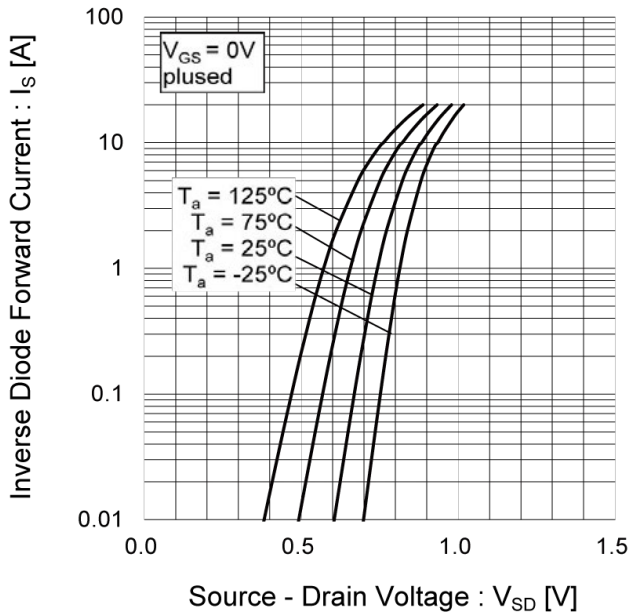
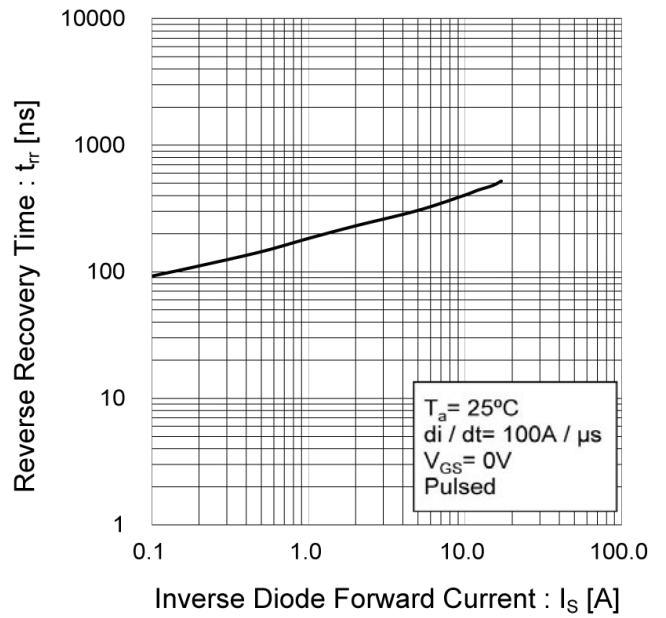


Fig.18 Reverse Recovery Time vs. Inverse Diode Forward Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



Fig.1-2 Switching Waveforms

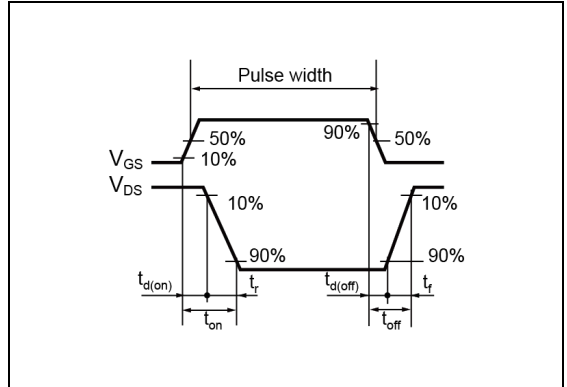


Fig.2-1 Gate Charge Measurement Circuit

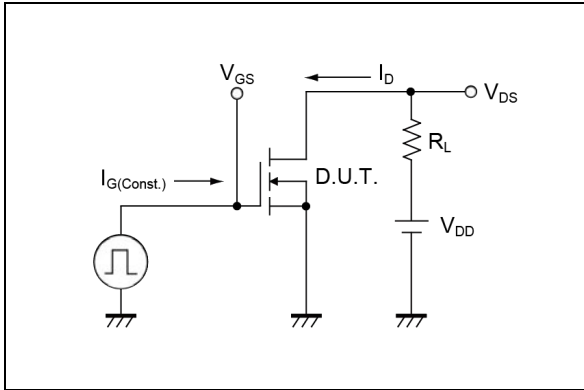


Fig.2-2 Gate Charge Waveform

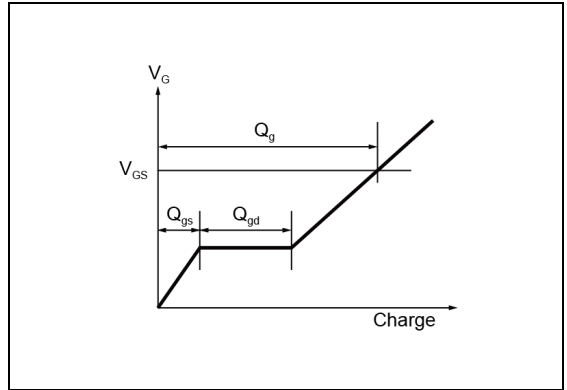


Fig.3-1 Avalanche Measurement Circuit

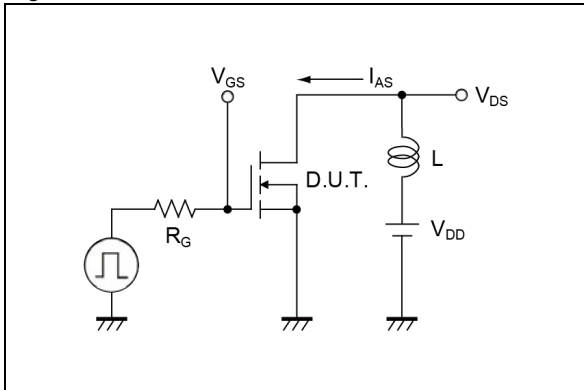


Fig.3-2 Avalanche Waveform

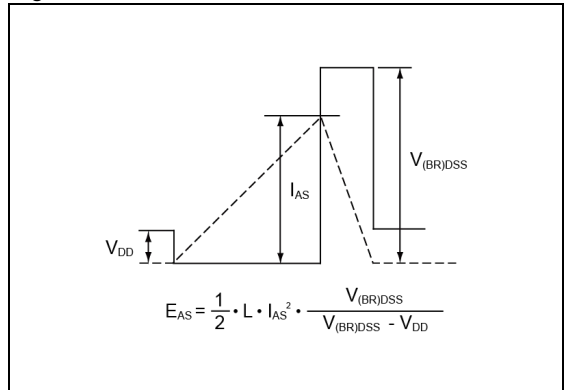


Fig.4-1 trr Measurement Circuit

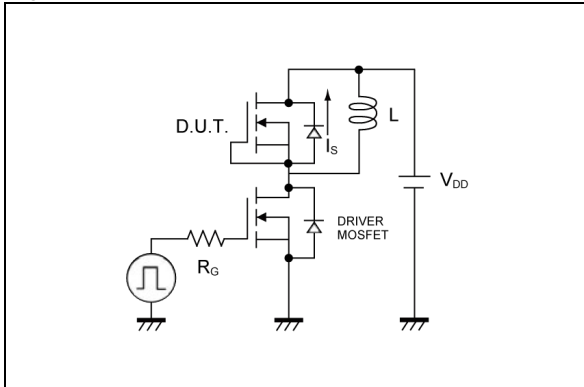
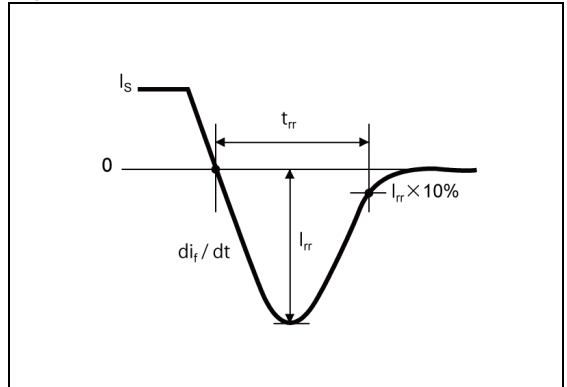


Fig.4-2 trr Waveform



●Dimensions



Pattern of terminal position areas
[Not a pattern of soldering pads]

| DIM | MILIMETERS | | INCHES | |
|-----|------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A1 | 0.00 | 0.30 | 0.000 | 0.012 |
| A2 | 4.30 | 4.70 | 0.169 | 0.185 |
| A3 | 0.25 | | 0.010 | |
| b | 0.68 | 0.98 | 0.027 | 0.039 |
| b2 | 8.90 | | 0.350 | |
| b3 | 1.14 | 1.44 | 0.045 | 0.057 |
| c | 0.30 | 0.60 | 0.012 | 0.024 |
| c1 | 1.10 | 1.50 | 0.043 | 0.059 |
| D | 9.80 | 10.40 | 0.386 | 0.409 |
| E | 8.80 | 9.20 | 0.346 | 0.362 |
| e | 2.54 | | 0.100 | |
| HE | 12.80 | 13.40 | 0.504 | 0.528 |
| L | 2.70 | 3.30 | 0.106 | 0.130 |
| L1 | 1.20 | | 0.047 | |
| L2 | 1.10 | | 0.043 | |
| L3 | 7.25 | | 0.285 | |
| L4 | 1.00 | | 0.039 | |
| Lp | 0.90 | 1.50 | 0.035 | 0.059 |
| x | - | 0.25 | - | 0.010 |

| DIM | MILIMETERS | | INCHES | |
|-----|------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| b5 | - | 1.23 | - | 0.049 |
| b6 | - | 10.40 | - | 0.409 |
| l1 | - | 2.10 | - | 0.083 |
| l2 | - | 7.55 | - | 0.297 |
| l3 | - | 13.40 | - | 0.528 |

Dimension in mm/inches

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|-----------|-----------|------------|-----------|
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| CLASS IV | | CLASS III | |

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- Confirm that operation temperature is within the specified range described in the product specification.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
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